

# Discontinued

RFM products are now Murata products.

SF2140A

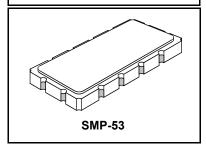
- · Precision SAW Filter
- Excellent Size-to-performance Ratio
- Hermetic 13.3 x 6.5 mm Surface-mount Case
- Complies with Directive 2002/95/EC (RoHS)



#### **Absolute Maximum Ratings**

Rating	Value	Units	
Input Power Level	+10	dBm	
Storage Temperature Range in Tape and Reel	-40 to +85	°C	
Operating Temperature Range	-40 to +85 °C		
Suitable for Lead-free Soldering - Maximum Soldering Profile	260 °C for 30 s		

# 140.0 MHz **SAW Filter**



### **Electrical Characteristics**

Characteristic	Sym	Notes	Min	Тур	Max	Units
Nominal Center Frequency	f <sub>C</sub>	1		140.0		MHz
Minimum Insertion loss	IL <sub>MIN</sub>			9.2	10.5	dB
1 dB Bandwidth			18.4	20.8		MHz
3 dB Bandwidth			20.0	21.8		MHz
35 dB Bandwidth				25.5	26.4	MHz
Amplitude Ripple, 130.9 to 149.1 MHz				0.75	1.0	dB <sub>P-P</sub>
Group Delay Ripple, 130.9 to 149.1 MHz				115	150	ns <sub>P-P</sub>
Group Delay				1.05		μs
Input VSWR, 0.9 to 149.1 MHz				2.0:1	2.5:1	dB
Output VSWR, 130.9 to 149.1 MHz				1.7:1	2.3:1	dB
Temp Coefficient				-93		ppm/°C
Attenuation Referenced to IL <sub>MIN</sub> :						
10 to 90 MHz			35	62		dB
190 to 120 MHz			40	54		dB
120.0 to 126.8 MHz			35	42		dB
154.7 to 160.0 MHz			35	45		dB
160 to 190 MHz			40	43		dB
190 to 800 MHz			35	62		dB

Case Style	SMP-53 13.3 X 6.5 mm Nominal Footprint
Lid Symbolization, YY=year, WW=week, S = shift	RFM SF2140A <u>YYWWS##</u>



# **CAUTION: Electrostatic Sensitive Device. Observe precautions for handling.**

Unless noted otherwise, all specifications apply over the operating temperature range with filter soldered to the specified demonstration board with impedance matching to 50  $\Omega$  and measured with 50  $\Omega$  network analyzer.

Unless noted otherwise, all frequency specifications are referenced to the nominal center frequency, fc.

Rejection is measured as attenuation below the minimum IL point in the passband. Rejection in final user application is dependent on PCB layout and external impedance matching design. See Application Note No. 42 for details.
"LRIP" or "L" after the part number indicates "low rate initial production" and "ENG" or "E" indicates "engineering prototypes."

The design, manufacturing process, and specifications of this filter are subject to change.

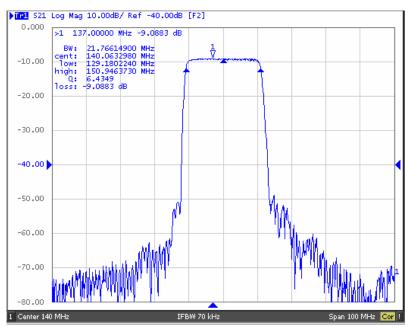
Either Port 1 or Port 2 may be used for either input or output in the design. However, impedances and impedance matching may vary between Port 1 and Port 2, so that the filter must always be installed in one direction per the circuit design.

US and international patents may apply.

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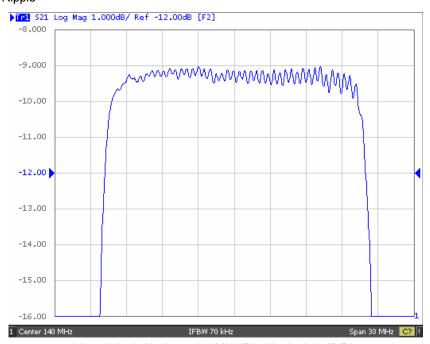
# **Frequency Characteristics:**

### 1. S21 Response



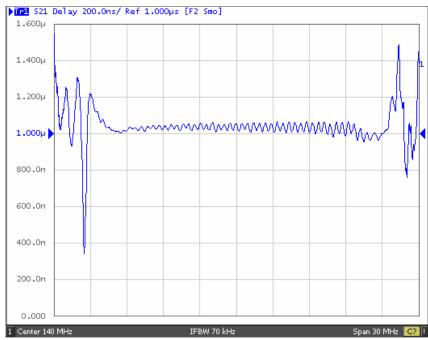
S21 Response Horizontal: 10 MHz/Div Vertical: 10 dB/Div

### 2. Passband Amplitude Ripple



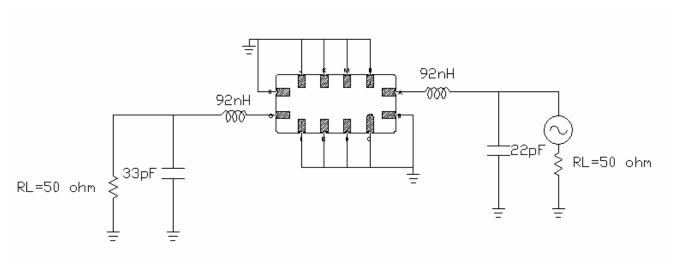
Inband ripple Horizontal: 3 MHz/Div Vertical: 1 dB/Div

# 3. Group Delay Ripple

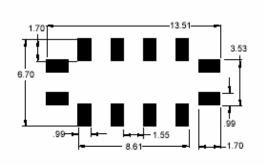


Horizontal: 3 MHz/Div Vertical: 200 nS/Div

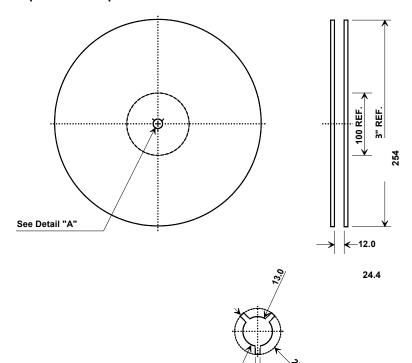
### **Measurement Circuits:**



# **PCB Footprint:**



# **Tape and Reel Specifications**

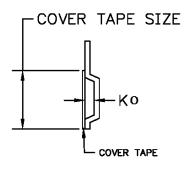


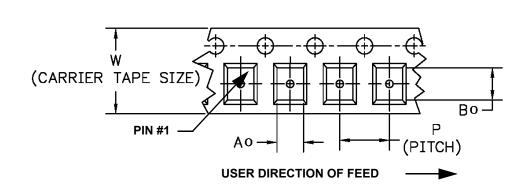
Quantity Per Reel	
100 Min	
1000 Max	

# **COMPONENT ORIENTATION and DIMENSIONS**

21.0

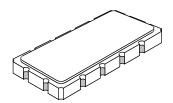
Carrier Tape Dimensions				
Ао	7.0 mm			
Во	13.8 mm			
Ко	2.0 mm			
Pitch	12.0 mm			
W	24.0 mm			





# **SMP-53 Case**

# 12-Terminal Ceramic Surface-Mount Case 13.3 x 6.5 mm Nominal Footprint



Case Dimensions						
Dimension	mm				Inches	
	Min	Nom	Max	Min	Nom	Max
Α	13.08	13.3	13.6	0.515	0.524	0.535
В	6.27	6.5	6.80	0.247	0.256	0.268
С			1.6			
D		1.5				
E		0.80				
Н		0.60				
Р		2.54				

Electrical Connections				
Connection	Terminals			
RF Input	11			
RF Input Ground	12			
RF Output	5			
RF Output Ground	6			
Ground	All others			

Materials				
Solder Pad Plating	0.3 to 1.0 μm Gold over 1.27 to 8.89 μm Nickel			
Lid Plating	2.0 to 3.0 µm Nickel			
Body	Al <sub>2</sub> O <sub>3</sub> Ceramic			
	Pb Free			

